

ABSTRACT

ADHESIVE CONTAINING POLYDIMETHYL SILOXANE

There is provided an adhesive which can be easily peeled off after polishing the back face of a wafer, and which has heat resistance and can be easily washed off. An
5 adhesive for peelably adhering between a support and a circuit-bearing face of a wafer and thereby processing a back face of the wafer, a peeling face upon peeling becomes selectable according to heating from the support side or heating from the wafer side when the adhesive is cured. The adhesive comprises a component (A) curing by hydrosilylation reaction and a component (B) containing a polydimethylsiloxane. The
10 component (B) is a polydimethylsiloxane having a viscosity of 1,100 mm²/s to 2,000,000 mm²/s. A forming method of a laminate comprising forming an adhesion layer by applying the adhesive to a surface of a first substrate, bonding a surface of a second substrate to the adhesion layer, and curing the adhesion layer by heating from the first substrate side. A peeling method comprising forming an adhesion layer by applying the
15 adhesive to a surface of a first substrate, bonding a surface of a second substrate to the adhesion layer, curing the adhesion layer by heating from the first substrate side to form a laminate, processing the laminate, and peeling off between the first substrate and the adhesion layer.